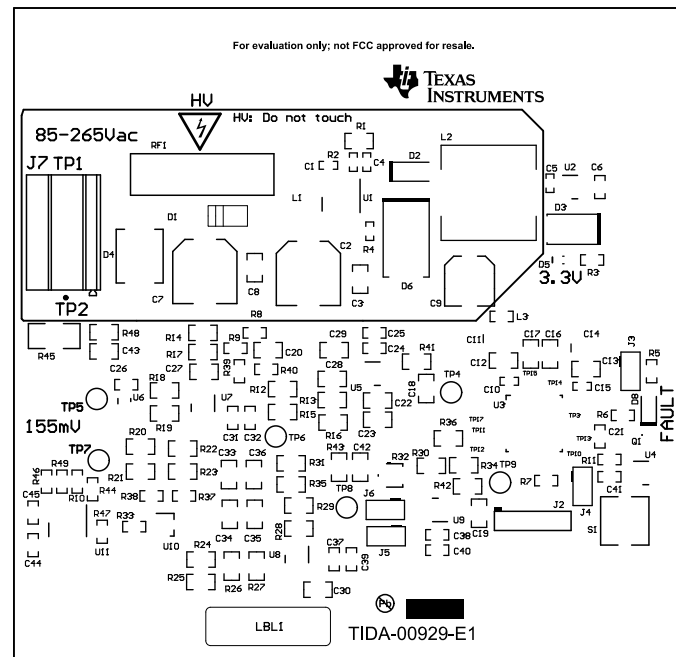


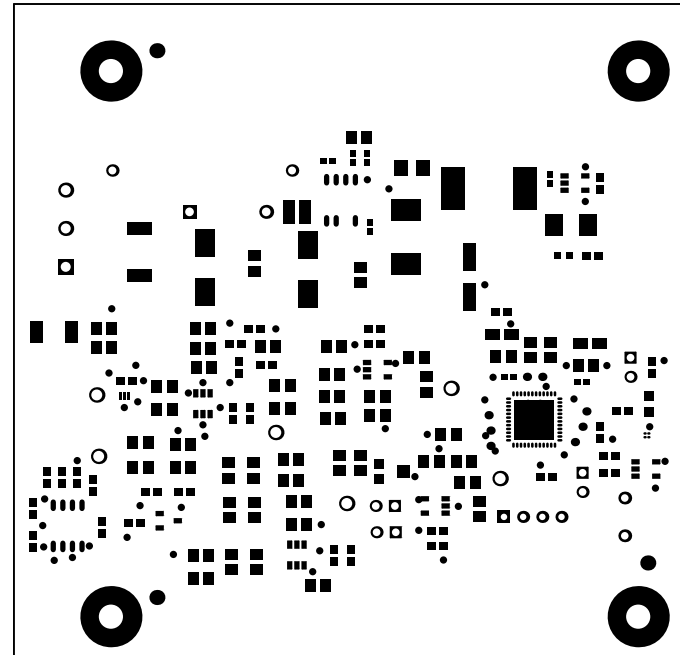
ZZ1



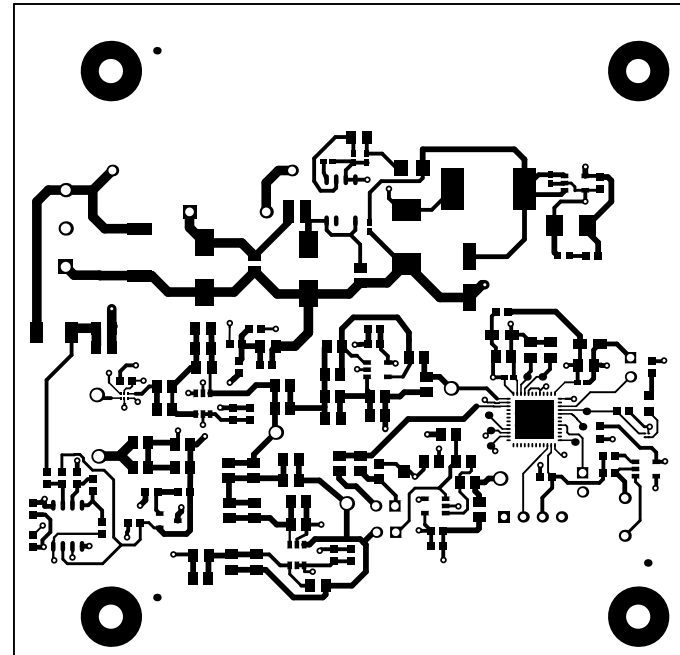
ZZ2

ZZ3
ZZ4

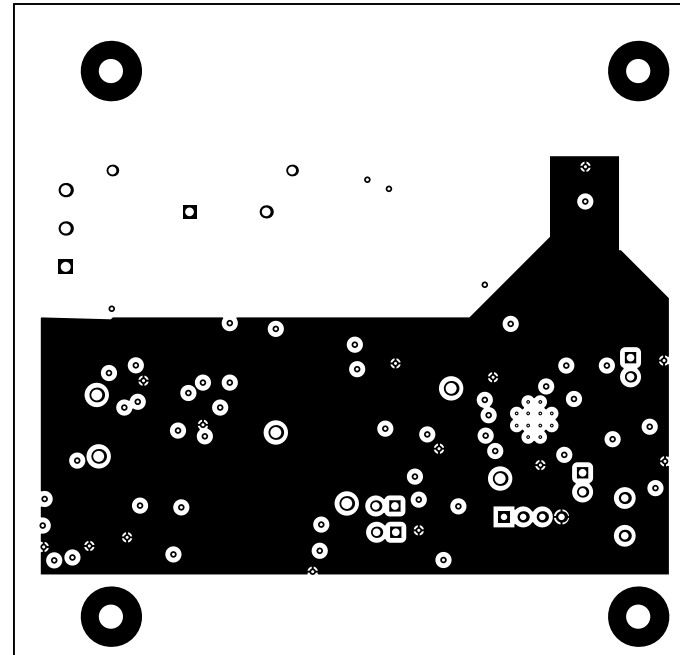
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00929		
PLOT NAME = Top Overlay	GENERATED : 2/13/2017 3:31:44 PM	TEXAS INSTRUMENTS	



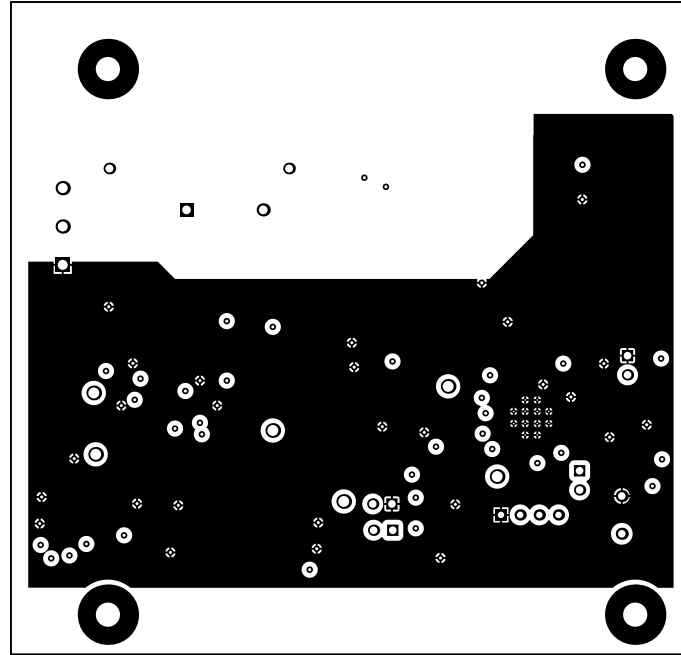
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00929		
PLOT NAME = Top Solder Mask	GENERATED : 2/13/2017 3:31:46 PM	TEXAS INSTRUMENTS	



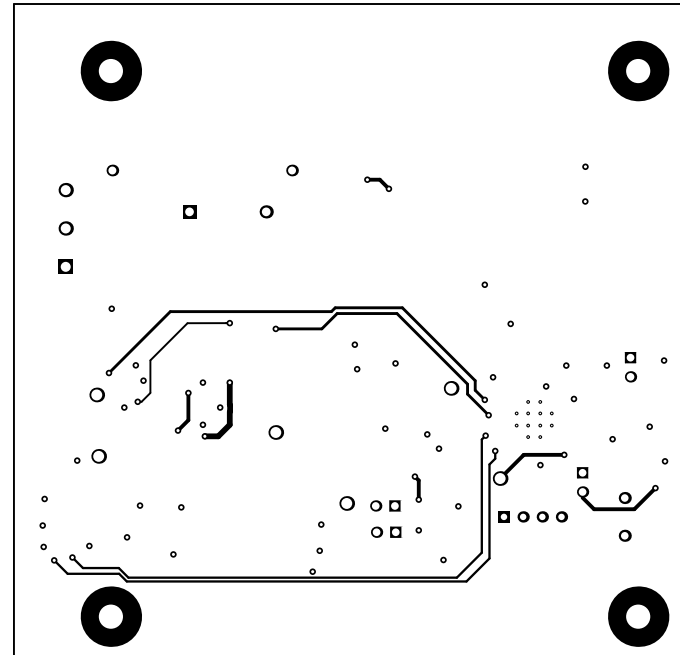
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00929		
PLOT NAME = Top Layer	GENERATED : 2/13/2017 3:31:46 PM	TEXAS INSTRUMENTS	



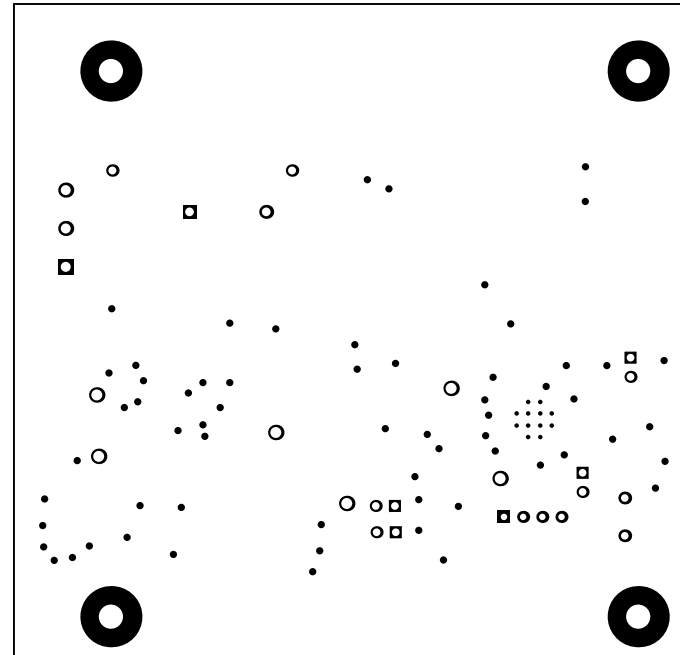
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00929		
PLOT NAME = Signal Layer 1	GENERATED : 2/13/2017 3:31:47 PM	TEXAS INSTRUMENTS	



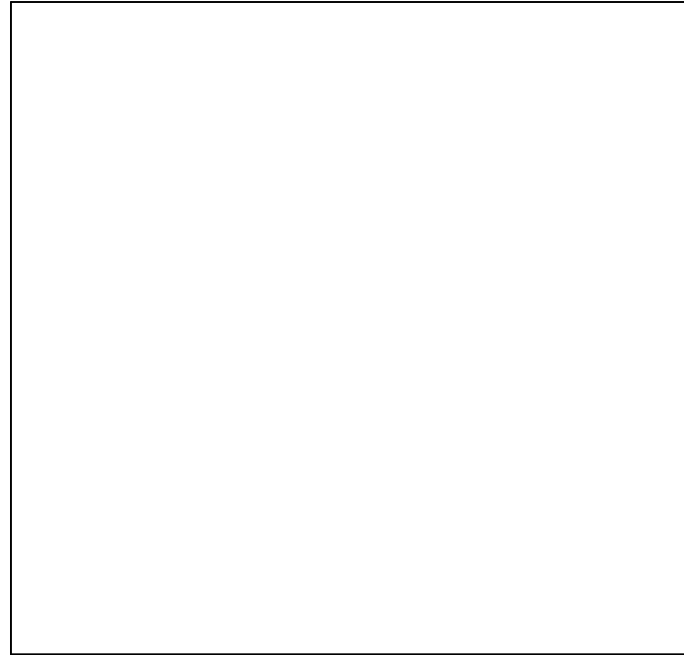
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00929		
PLOT NAME = Signal Layer 2	GENERATED : 2/13/2017 3:31:48 PM	TEXAS INSTRUMENTS	



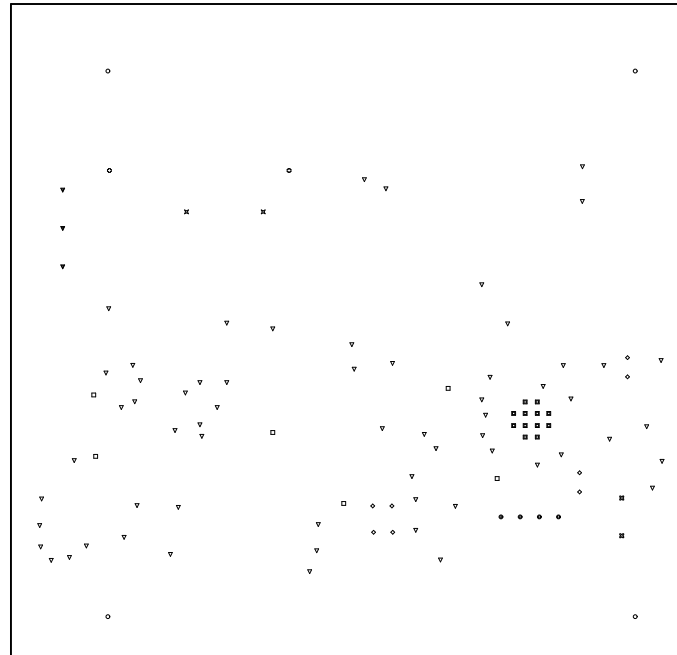
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00929		
PLOT NAME = Bottom Layer	GENERATED : 2/13/2017 3:31:49 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00929		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/13/2017 3:31:50 PM	TEXAS INSTRUMENTS	

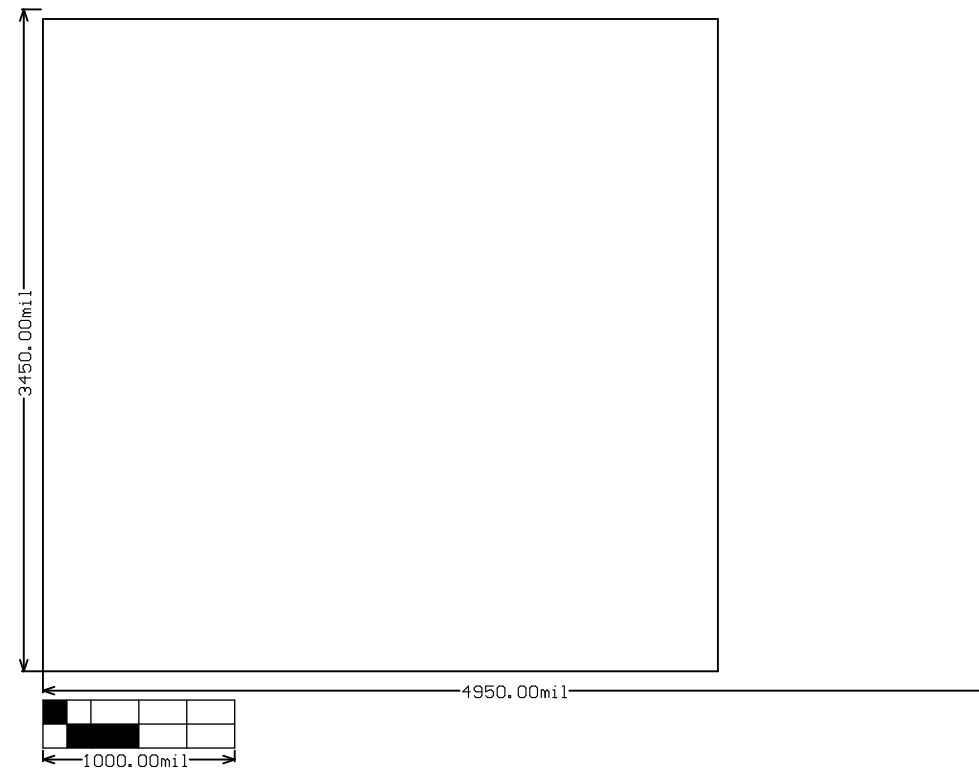


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00929		
PLOT NAME = Bottom Overlay	GENERATED : 2/13/2017 3:31:51 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
■	12	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	62	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
◇	8	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
▽	3	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
□	6	57.00mil (1.448mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	105 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00929		
PLOT NAME = Drill Drawing	GENERATED : 2/13/2017	3:31:52 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00929	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00929		
PLOT NAME = Board Dimensions	GENERATED : 2/13/2017 3:31:53 PM	TEXAS INSTRUMENTS	

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